


SECTION A-A

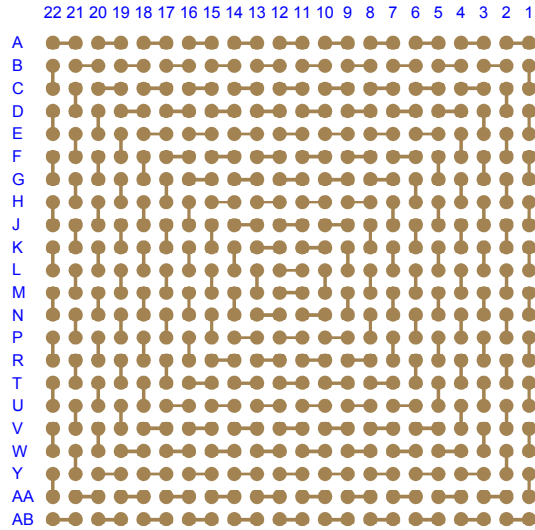
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.635 (25 MIL).
- 4) SOLDER MASK DEFINED PAD OPENING: 0.508mm (20 MIL).
- 5) PAD Cu DIAMETER: 0.635mm (25 MIL).
- 6) SUBSTRATE MATERIAL: BT (ALTERNATE FR4).
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

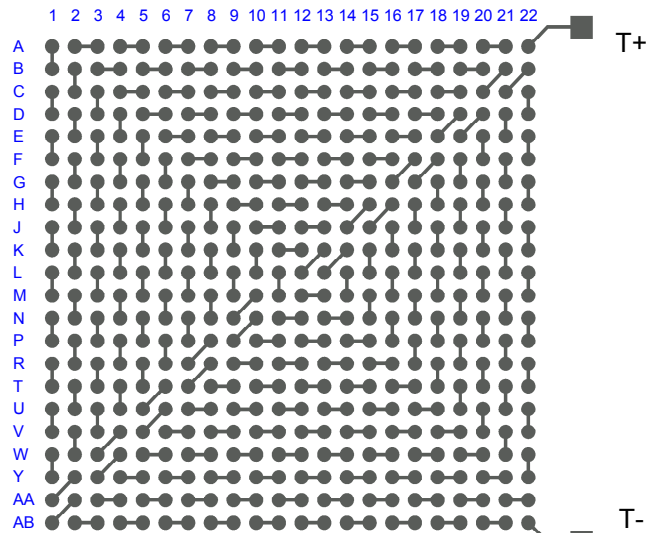
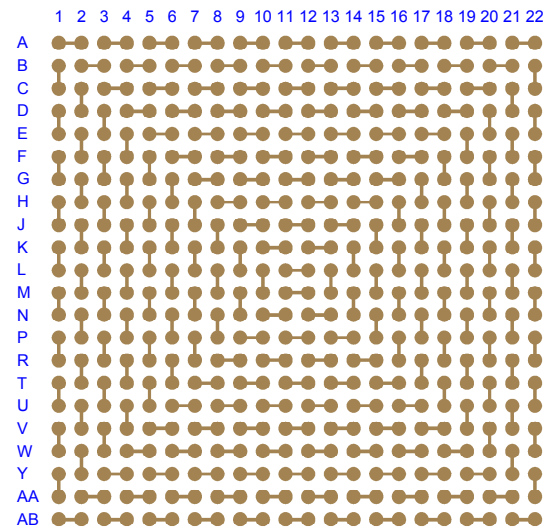
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-Free	RoHS	Si DIE
LBGA484T1.0C-DC229AD	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
LBGA484T1.0C-DC229A	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
LBGA484T1.0-DC229AD	Sn63/Pb37	NO	NO	YES
LBGA484T1.0-DC229A	Sn63/Pb37	NO	NO	NO

APPROVALS	DATE				
DRAWN T.Au	12/26/13				
ENG M. Hart	12/26/13	TITLE		LBGA484T1.0-DC229A DAISY CHAIN DUMMY	
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		3.7:1	A	512290	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 2
REVISED					

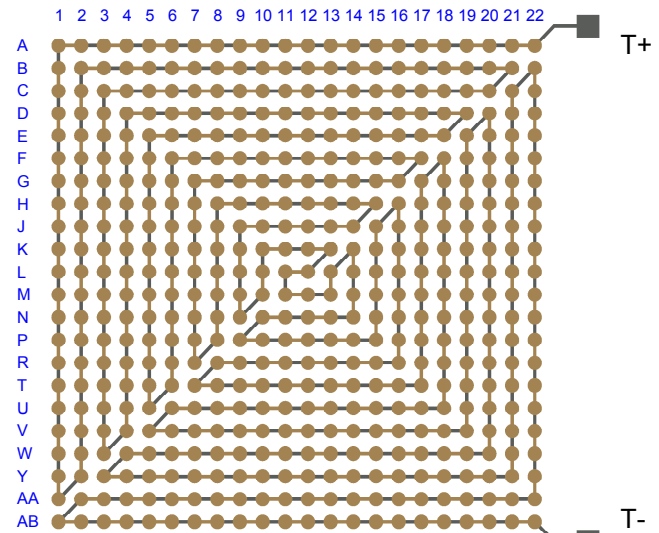
BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.635mm (25 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm (6 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.508mm (20 MIL).

TopLine®			
TITLE		LBGA484T1.0-DC229A DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
3:1	A	512290	A
DO NOT SCALE DRAWING			SHEET 2 OF 2